



US 20240244941A1

(19) **United States**

(12) **Patent Application Publication**
JANG et al.

(10) **Pub. No.: US 2024/0244941 A1**

(43) **Pub. Date: Jul. 18, 2024**

(54) **MASK-SUPPORT ASSEMBLY, PRODUCING METHOD THEREOF, AND MASK-FRAME ASSEMBLY**

Publication Classification

(51) **Int. Cl.**
H10K 71/16 (2006.01)
C23C 14/04 (2006.01)
(52) **U.S. Cl.**
CPC **H10K 71/166** (2023.02); **C23C 14/042** (2013.01)

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(21) Appl. No.: **18/392,401**

(22) Filed: **Dec. 21, 2023**

(30) **Foreign Application Priority Data**

Jan. 13, 2023 (KR) 10-2023-0005523
Jan. 20, 2023 (KR) 10-2023-0008615
Jan. 20, 2023 (KR) 10-2023-0008616

(57) **ABSTRACT**

The present invention relates to a mask-support assembly, a producing method thereof, and a mask-frame assembly. The producing method of a mask-support assembly according to the present invention may include the steps of: (a) preparing a conductive substrate; (b) forming a mask including a mask pattern on a first surface of the conductive substrate; (c) reducing a thickness of the conductive substrate on a second surface opposite to the first surface of the conductive substrate; and (d) forming a support including an edge portion and a grid portion by etching the conductive substrate on the second surface thereof.

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